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(54) **Title**: METHODS FOR IMPROVING THE FLUX COMPATIBILITY OF UNDERFILL FORMULATIONS

(57) **Abstract**: In accordance with the present invention, it has been discovered that the addition of one or more cationic catalyst(s), such as onium salts as defined herein, provides improved flux compatibility of underfill formulations in the presence of flux, flux residues and/or reaction products thereof. Accordingly, there are provided methods for improving the flux compatibility of underfill formulations in the presence of flux, flux residues and/or reaction products thereof. In accordance with another embodiment of the present invention, there are provided methods for improving HAST performance of underfill formulations, especially in the presence of flux, flux residues and/or reaction products thereof. In accordance with another embodiment of the present invention, there are provided methods for preparing underfill formulations having improved flux compatibility, especially in the presence of flux, flux residues and/or reaction products thereof. In yet another embodiment of the present invention, there are provided methods for adhesively attaching and/or encapsulating electronic components, especially in the presence of flux, flux residues and/or reaction products thereof. In a further embodiment of the present invention, there are provided articles produced by the above-described processes.



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